

RECENT PROGRESS IN HIGH-OUTPUT-VOLTAGE SILICON SOLAR CELLS*

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High-quality shallow-junction planar solar cells have been fabricated on 0.1 Ω -cm float zone refined silicon using Emulsitone N250 spin-on dopant, aluminum-alloyed back contacts, and "dot" contact front grids (ref. 1). Use of a process similar to the NASA-Lewis double-diffusion process (ref. 2) has reduced shunt leakage and junction recombination currents while adding 10 mV to the best open-circuit voltages obtained from the single-diffusion process.

The present status of a 0.1- Ω -cm covered solar cell (153-mA short-circuit, 654-mV open-circuit voltage, 77.5-mW maximum power, and 14.4-percent AMO efficiency) is characterized in figure 1 before and after covering. The short-circuit current (ISC) is about 6 percent less than that observed in typical higher resistivity (>1 - Ω -cm) violet cells (ref. 3) but the open-circuit voltage (VOC) is about 9 percent higher. During covering or subsequent handling, the cell fill factor was reduced in an unexplained manner (analysis indicates a lowered shunt resistance). If it had been maintained, the maximum power would have exceeded 79.5 mW.

The quantum-yield data are presented in figure 2 along with data from a deeper junction cell ($x_j \sim 1.6 \mu\text{m}$) from the same batch and a shallow junction ($x_j \sim 0.1 \mu\text{m}$) cell made by a different process. An important feature of this figure is the unusual shape of the set A curves. A conventional cell with a surface dead layer displays a much more abrupt drop in the short wavelength region rather than the more gentle slopes observed in figure 2 below 700 nm. It would appear that the double-diffusion process alters the cell characteristics in a manner quite different than expected from a simple change in the diffused layer (see ref. 2 for a possible explanation). Set A had an overnight diffusion with N250 at 880°C followed by different etch times prior to an N250 diffusion at 820°C for 15 minutes; set B was diffused with N250 at 820°C for 15 minutes.

The advantages of a 2-step diffusion process are delineated by comparisons of the data from two sets of cells (table I). The data indicate several differences resulting from a prediffusion; most important are a 10-mV increase in VOC and an improved fill factor of set A. The improved VOC is explained by the lower bulk dark current (JD); the better fill factor (FF) is

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due to the lower preexponential of the $n = 2$ term (JRC) and higher shunt resistance (RSH). The penalty is reduced ISC and blue response (IB), as seen in figure 2. The long wavelength response ($\lambda > 1000 \text{ nm}$) and the currents (I_{sc}) from γ -ray irradiation of the two sets are nearly equal and indicate diffusion lengths comparable to or greater than the cell thickness ($200 \mu\text{m}$). This point is supported by the values of ISC in set B, which are almost as high as those for 1- to 2- Ω -cm violet cells.

Efforts are continuing to better understand the mechanism responsible for increased voltage resulting from the double-diffusion process. Once this mechanism is understood, work can be directed toward further voltage gains and reduction of short-circuit current losses.

REFERENCES

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3. Haynos, J.G.; Allison, J. F.; Arndt, R. A.; and Meulenberg, A.: The COMSAT Non-Reflective Silicon Solar Cell: A Second Generation Improved Cell, International Conf. on Photovoltaic Power Generation, Sept. 1974, Hamburg, Germany, Proc., pp. 487-500.

Table I. UNCOVERED CHARACTERISTICS OF A BATCH OF SINGLY DIFFUSED CELLS (SET B)
AND A BATCH OF DOUBLY DIFFUSED CELLS (SET A)

Cell No.	Process	ISC (mA)	VOC (mV)	IB (mA)	F.F.	I_Y^a	JD (pA)	JRC (nA)	RSH (Ω)
1	N250	130.4	647	29.6	0.82	6.9	0.32	20	365
2	1.6 μm	123.7	642	27.9	0.80	6.8	0.37	32	111
3	N250	133.9	640	33.3	0.80	6.6	0.44	32	1 K
4	$\sim 0.9 \mu\text{m}$	136.7	646	33.5	0.80	6.7	0.35	31	540
5	N250	142.8	644	37.3	0.80	6.5	0.40	36	1 K
6	$\sim 0.3 \mu\text{m}$	143.1	646	37.2	0.80	6.6	0.35	43	1 K
7	N250	142.8	648	37.5	0.80	6.5	0.31	50	1 K
8	$\sim 0.15 \mu\text{m}$	142.6	650	37.3	0.80	6.2 ^c	0.3	39	1 K
Set A ^b									
1		149.3	629	41	0.73	6.8	0.54	111	46
2	N250	150.8	630	40.8	0.71	7.2	0.54	110	37
3	0.1 μm	150.1	637	40.8	0.77	6.8	0.46	88	134
4		149.2	634	41	0.73	6.4	0.47	97	49
Set B									

^a An I_Y of 7.0 corresponds to a diffusion length of $\geq 180 \mu\text{m}$.

^b Variable etch depth.

^c Measured with coverslide.

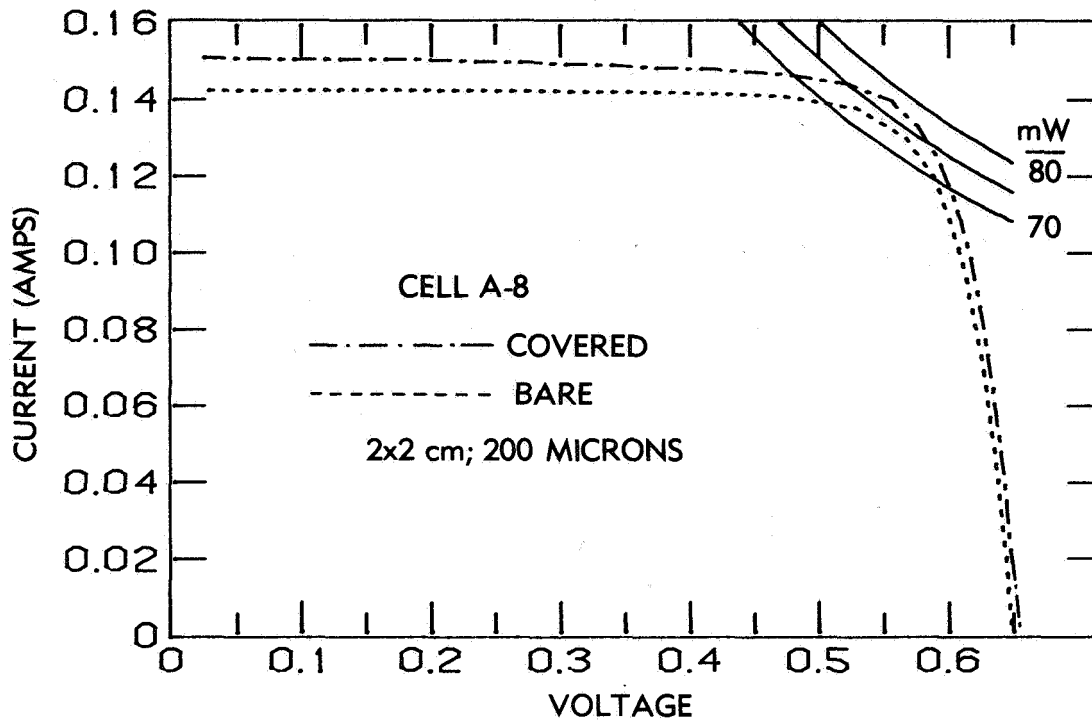


Figure 1. IV Curves for Cell Set A-8 Bare (Dots) and Covered (Broken) Under Simulated AM0 Conditions

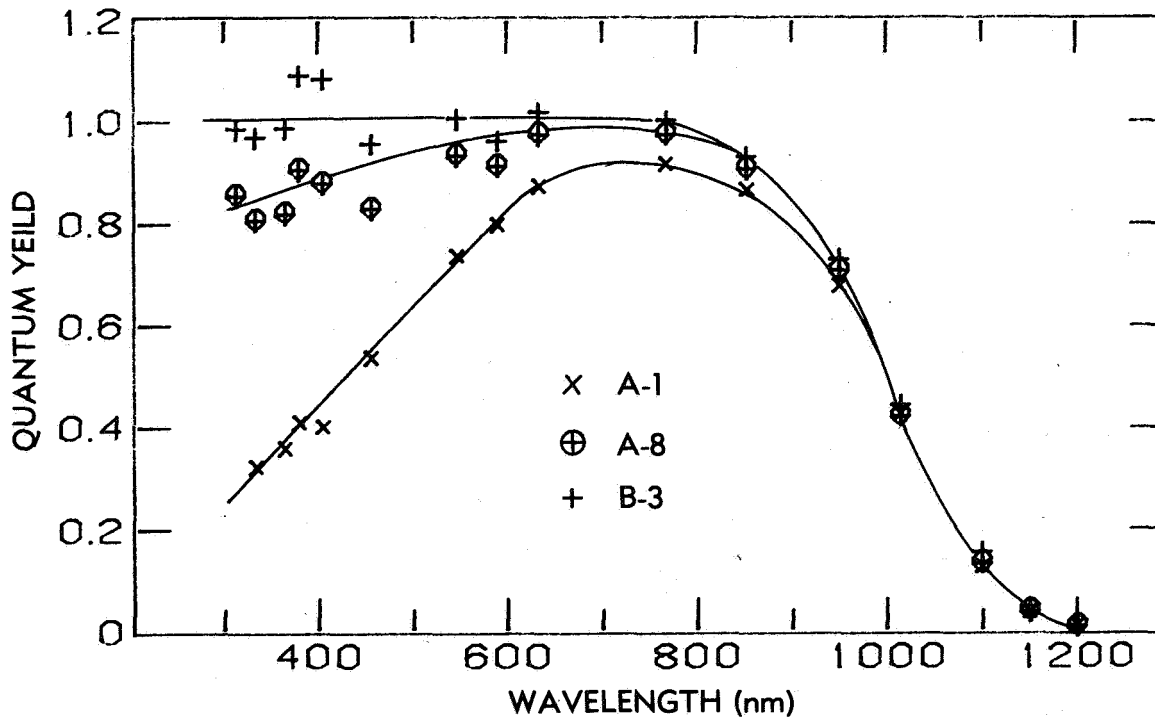


Figure 2. Quantum Yield Results for Cell A-8 ($x_j \approx 0.15 \mu\text{m}$) along with Shallow (B-3) and Deep (A-1) Junction Cells